

## General Description

OST40N120HMF uses advanced Oriental-Semi's patented Trident-Gate Bipolar Transistor (TGBT™) technology to provide extremely low  $V_{CE(sat)}$ , low gate charge, and excellent switching performance. This device is suitable for mid to high range switching frequency converters.

## Features

- Advanced TGBT™ technology
- Excellent conduction and switching loss
- Excellent stability and uniformity
- Fast and soft antiparallel diode



## Applications

- Induction converters
- Uninterruptible power supplies

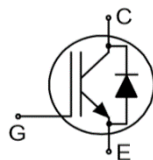
## Key Performance Parameters

Parameter	Value	Unit
$V_{CES, min} @ 25^{\circ}C$	1200	V
Maximum junction temperature	175	$^{\circ}C$
$I_C, pulse$	160	A
$V_{CE(sat), typ} @ V_{GE}=15V$	1.45	V
$Q_g$	214	nC

## Marking Information

Product Name	Package	Marking
OST40N120HMF	TO247	OST40N120HM

## Package & Pin Information



**Absolute Maximum Ratings** at  $T_{vj}=25^{\circ}\text{C}$  unless otherwise noted

Parameter	Symbol	Value	Unit
Collector emitter voltage	$V_{CES}$	1200	V
Gate emitter voltage	$V_{GES}$	$\pm 20$	V
Transient gate emitter voltage, $T_P \leq 0.5\mu\text{s}$ , $D < 0.001$		$\pm 25$	V
Continuous collector current <sup>1)</sup> , $T_C = 25^{\circ}\text{C}$	$I_C$	56	A
Continuous collector current <sup>1)</sup> , $T_C = 100^{\circ}\text{C}$		40	A
Pulsed collector current <sup>2)</sup> , $T_C = 25^{\circ}\text{C}$	$I_{C, pulse}$	160	A
Diode forward current <sup>1)</sup> , $T_C = 25^{\circ}\text{C}$	$I_F$	56	A
Diode forward current <sup>1)</sup> , $T_C = 100^{\circ}\text{C}$		40	A
Diode pulsed current <sup>2)</sup> , $T_C = 25^{\circ}\text{C}$	$I_{F, pulse}$	160	A
Power dissipation <sup>3)</sup> , $T_C = 25^{\circ}\text{C}$	$P_D$	357	W
Power dissipation <sup>3)</sup> , $T_C = 100^{\circ}\text{C}$		179	W
Operation and storage temperature	$T_{stg}, T_{vj}$	-55 to 175	$^{\circ}\text{C}$
Short circuit withstand time $V_{GE} = 15\text{ V}$ , $V_{CC} \leq 600\text{ V}$ Allowed number of short circuits < 1000 Time between short circuits: $\geq 1.0\text{ S}$ $T_{vj} = 150^{\circ}\text{C}$	$t_{sc}$	10	$\mu\text{s}$

**Thermal Characteristics**

Parameter	Symbol	Value	Unit
IGBT thermal resistance, junction-case	$R_{\theta JC}$	0.42	$^{\circ}\text{C}/\text{W}$
Diode thermal resistance, junction-case	$R_{\theta JC}$	0.75	$^{\circ}\text{C}/\text{W}$
Thermal resistance, junction-ambient <sup>4)</sup>	$R_{\theta JA}$	40	$^{\circ}\text{C}/\text{W}$

**Electrical Characteristics** at  $T_{vj}=25^{\circ}\text{C}$  unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Collector-emitter breakdown voltage	$V_{(BR)CES}$	1200			V	$V_{GE}=0\text{ V}$ , $I_C=0.5\text{ mA}$
Collector-emitter saturation voltage	$V_{CE(sat)}$		1.45	1.8	V	$V_{GE}=15\text{ V}$ , $I_C=40\text{ A}$ $T_{vj}=25^{\circ}\text{C}$
			1.65		V	$V_{GE}=15\text{ V}$ , $I_C=40\text{ A}$ , $T_{vj}=125^{\circ}\text{C}$
			1.8			$V_{GE}=15\text{ V}$ , $I_C=40\text{ A}$ , $T_{vj}=175^{\circ}\text{C}$
Gate-emitter threshold voltage	$V_{GE(th)}$	4.8	5.8	6.8	V	$V_{CE}=V_{GE}$ , $I_D=0.5\text{ mA}$
Diode forward voltage	$V_F$		1.9	2.1	V	$V_{GE}=0\text{ V}$ , $I_F=40\text{ A}$ $T_{vj}=25^{\circ}\text{C}$
			1.6			$V_{GE}=0\text{ V}$ , $I_F=40\text{ A}$ , $T_{vj}=125^{\circ}\text{C}$
			1.5			$V_{GE}=0\text{ V}$ , $I_F=40\text{ A}$ , $T_{vj}=175^{\circ}\text{C}$
Gate-emitter leakage current	$I_{GES}$			100	nA	$V_{CE}=0\text{ V}$ , $V_{GE}=20\text{ V}$
Zero gate voltage collector current	$I_{CES}$			10	$\mu\text{A}$	$V_{CE}=1200\text{V}$ , $V_{GE}=0\text{ V}$

### Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	$C_{ies}$		11270		pF	$V_{GE}=0\text{ V}$ , $V_{CE}=25\text{ V}$ , $f=100\text{ kHz}$
Output capacitance	$C_{oes}$		242		pF	
Reverse transfer capacitance	$C_{res}$		10		pF	
Turn-on delay time	$t_{d(on)}$		120		ns	$V_{GE}=15\text{ V}$ , $V_{CC}=600\text{ V}$ , $R_G=10\ \Omega$ , $I_C=40\text{ A}$
Rise time	$t_r$		88		ns	
Turn-off delay time	$t_{d(off)}$		246		ns	
Fall time	$t_f$		160		ns	
Turn-on energy	$E_{on}$		3.14		mJ	
Turn-off energy	$E_{off}$		1.02		mJ	
Turn-on delay time	$t_{d(on)}$		112		ns	$V_{GE}=15\text{ V}$ , $V_{CC}=600\text{ V}$ , $R_G=10\ \Omega$ , $I_C=20\text{ A}$
Rise time	$t_r$		51		ns	
Turn-off delay time	$t_{d(off)}$		284		ns	
Fall time	$t_f$		148		ns	
Turn-on energy	$E_{on}$		1.32		mJ	
Turn-off energy	$E_{off}$		0.53		mJ	

### Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	$Q_g$		214		nC	$V_{GE}=15\text{ V}$ , $V_{CC}=960\text{ V}$ , $I_C=40\text{ A}$
Gate-emitter charge	$Q_{ge}$		103		nC	
Gate-collector charge	$Q_{gc}$		40		nC	

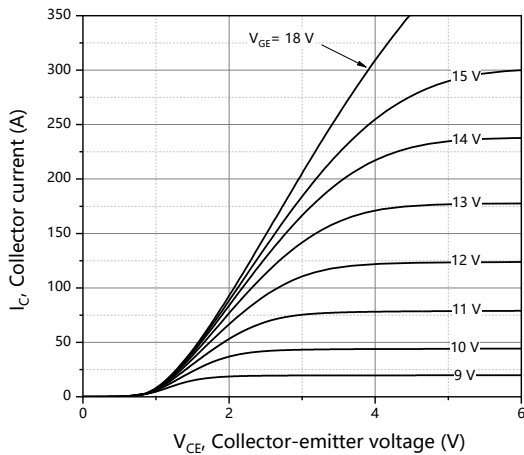
### Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode reverse recovery time	$t_{rr}$		293		ns	$V_R=600\text{ V}$ , $I_F=40\text{ A}$ , $di_F/dt=500\text{ A}/\mu\text{s}$ $T_{vj}=25^\circ\text{C}$
Diode reverse recovery charge	$Q_{rr}$		2.7		$\mu\text{C}$	
Diode peak reverse recovery current	$I_{rrm}$		25		A	

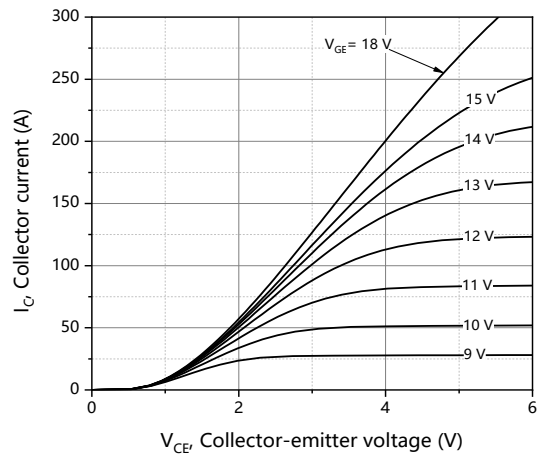
### Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3)  $P_d$  is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_a=25^\circ\text{C}$ .

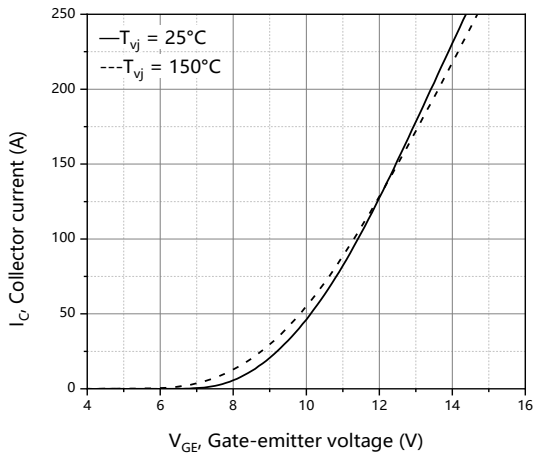
**Electrical Characteristics Diagrams**



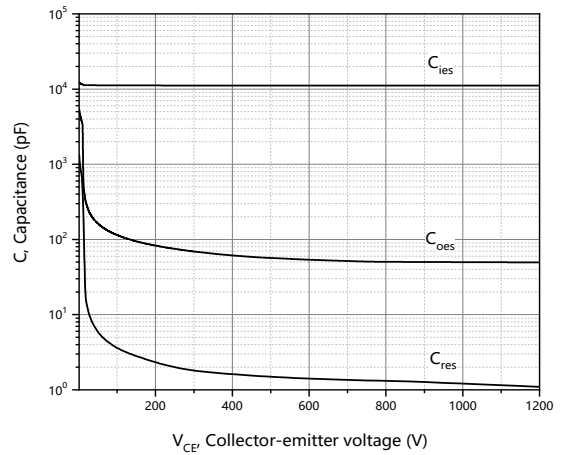
**Figure 1. Typical output characteristics**  
( $T_{vj}=25^{\circ}\text{C}$ )



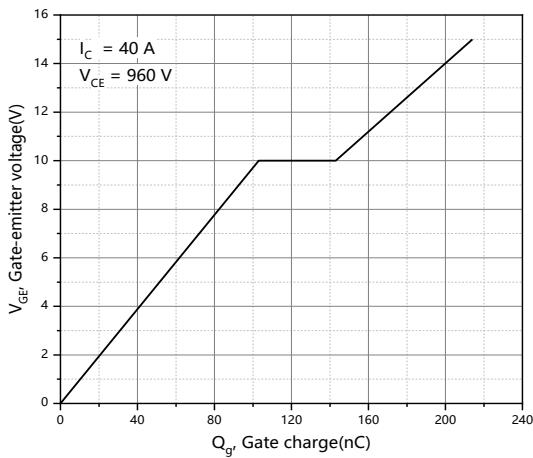
**Figure 2. Typical output characteristics**  
( $T_{vj}=150^{\circ}\text{C}$ )



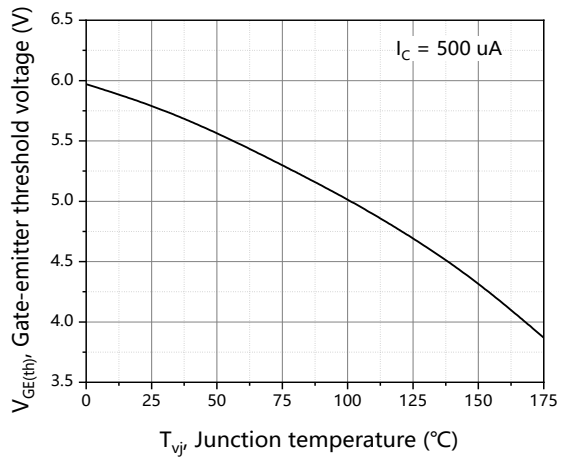
**Figure 3. Typical transfer characteristics**  
( $V_{ce}=20\text{V}$ )



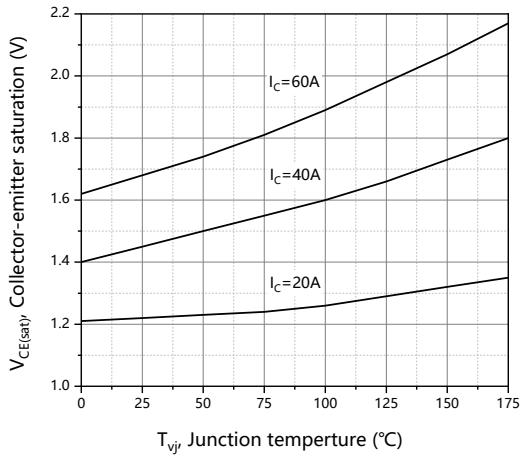
**Figure 4. Typical capacitance**  
( $V_{ge}=0\text{V}$ ,  $f=100\text{ kHz}$ )



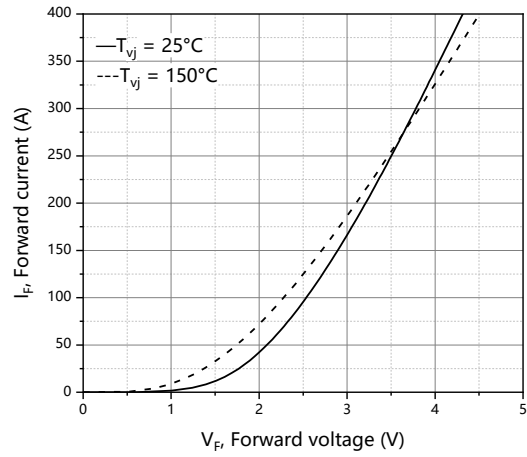
**Figure 5. Typical gate charge**



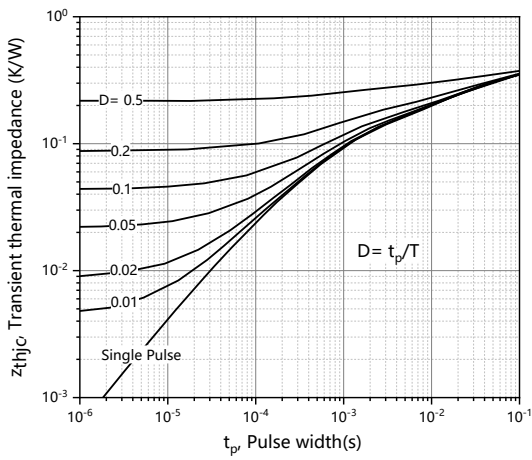
**Figure 6. Gate-emitter threshold voltage**



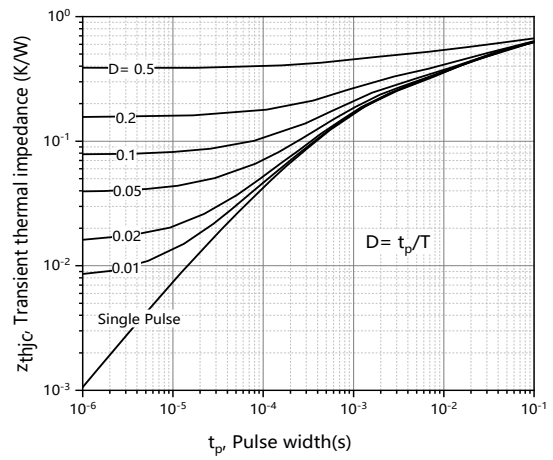
**Figure 7. Typical collector-emitter voltage**



**Figure 8. Forward characteristic of diode**

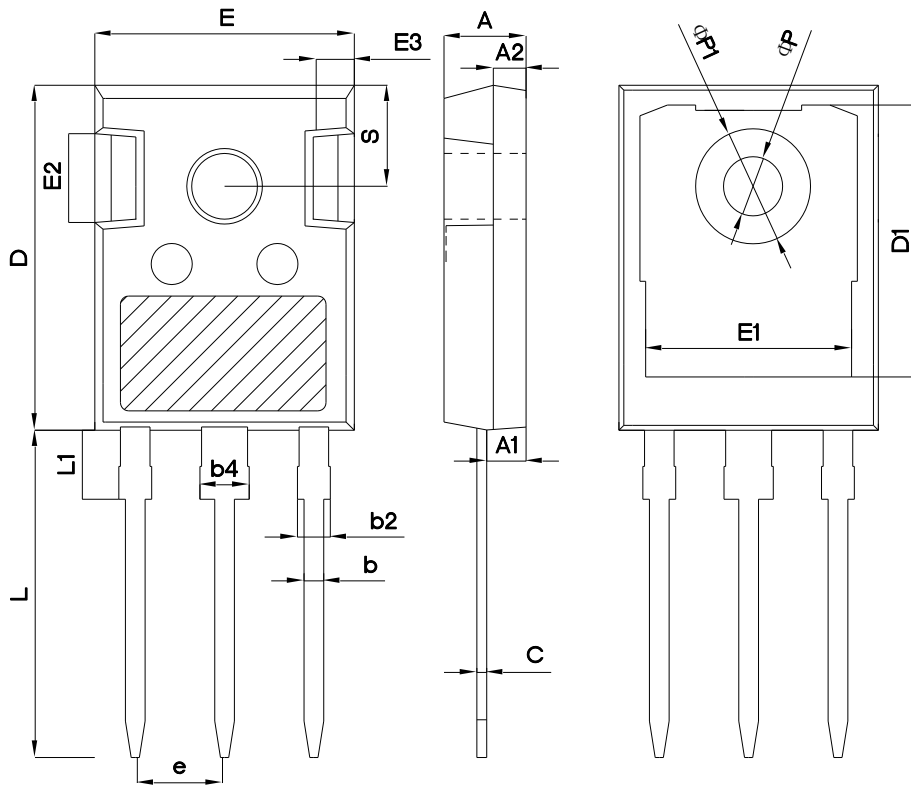


**Figure 9. IGBT transient thermal impedance**



**Figure 10. Diode transient thermal impedance**

**Package Information**



Symbol	mm		
	Min	Nom	Max
A	4.80	5.00	5.20
A1	2.21	2.41	2.59
A2	1.85	2.00	2.15
b	1.11	1.21	1.36
b2	1.91	2.01	2.21
b4	2.91	3.01	3.21
c	0.51	0.61	0.75
D	20.80	21.00	21.30
D1	16.25	16.55	16.85
E	15.50	15.80	16.10
E1	13.00	13.30	13.60
E2	4.80	5.00	5.20
E3	2.30	2.50	2.70
e	5.44 BSC		
L	19.82	19.92	20.22
L1	-	-	4.30
ΦP	3.40	3.60	3.80
ΦP1	-	-	7.30
S	6.15 BSC		

Version 1: TO247-P package outline dimension

## Ordering Information

Package Type	Units/ Tube	Tubes/ Inner Box	Units/ Inner Box	Inner Boxes/ Carton Box	Units/ Carton Box
TO247-P	30	11	330	6	1980

## Product Information

Product	Package	Pb Free	RoHS	Halogen Free
OST40N120HMF	TO247	yes	yes	yes

## Legal Disclaimer

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